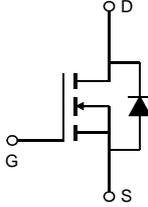


N-Channel Enhancement Mode Power MOSFET

<p>Features</p> <ul style="list-style-type: none"> • 30V/30A • $R_{DS(ON)} = 7.5m\Omega(Typ.)@V_{GS}=10V$ • $R_{DS(ON)} = 9.3m\Omega(Typ.)@V_{GS}=4.5V$ • Super High Dense Cell Design • Fast Switching Speed • Low gate Charge • 100% avalanche tested • Lead Free and Green Devices Available <p>Applications</p> <ul style="list-style-type: none"> • Switching Application Systems 	 <p>PDFN 3333 top view</p>  <p>Schematic diagram</p>
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Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
--------	-----------	--------	------

Common Ratings ($T_C=25^\circ C$ Unless Otherwise Noted)

V_{DSS}	Drain-Source Voltage	30	V	
V_{GSS}	Gate-Source Voltage	± 20		
T_J	Maximum Junction Temperature	150	$^\circ C$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$	
I_S	Diode Continuous Forward Current	$T_C=25^\circ C$	30	A

Mounted on Large Heat Sink

$I_{DP}^{①}$	300 μs Pulse Drain Current Tested	$T_C=25^\circ C$	100	A
$I_D^{②}$	Continuous Drain Current@ $T_C(V_{GS}=10V)$	$T_C=25^\circ C$	30	A
	Continuous Drain Current@ $T_A(V_{GS}=10V)^{③}$	$T_A=25^\circ C$	9.8	
P_D	Maximum Power Dissipation@ T_C	$T_C=25^\circ C$	30	W
	Maximum Power Dissipation@ $T_A^{③}$	$T_A=25^\circ C$	3.8	

Notes:

- ① Pulse width limited by safe operating area.
- ② Calculated continuous current based on maximum allowable junction temperature.
- ③ When mounted on 1 inch square copper board, $t \leq 10sec$.
- ④ Limited by T_{Jmax} , $I_{AS} = 13A$, $V_{DD} = 24V$, $R_G = 50\Omega$, Starting $T_J = 25^\circ C$.
- ⑤ Pulse test; Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- ⑥ Guaranteed by design, not subject to production testing.

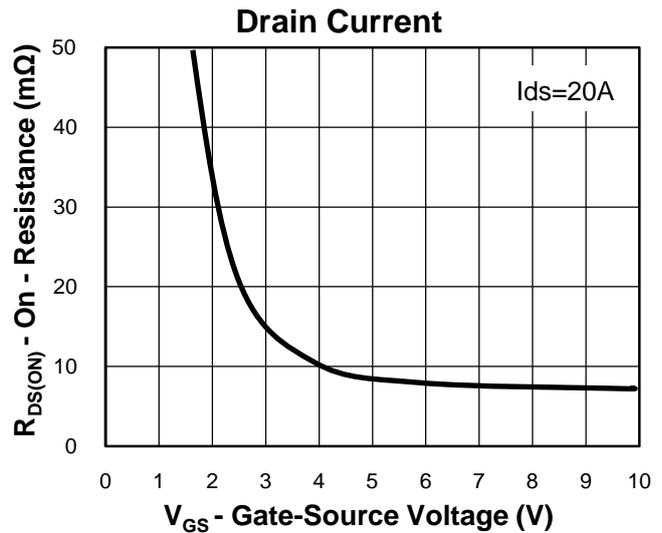
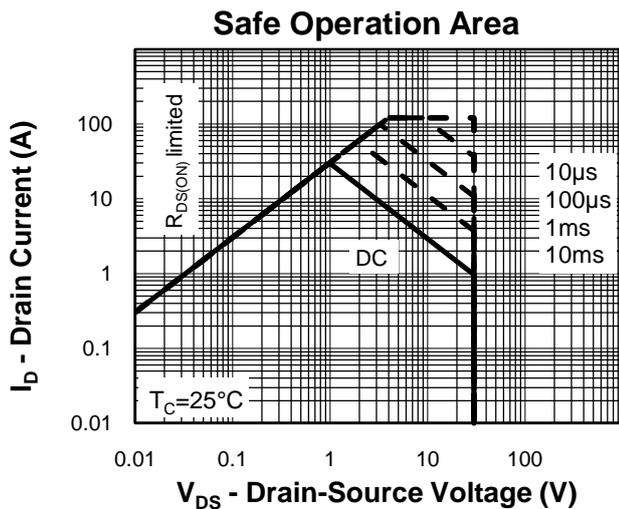
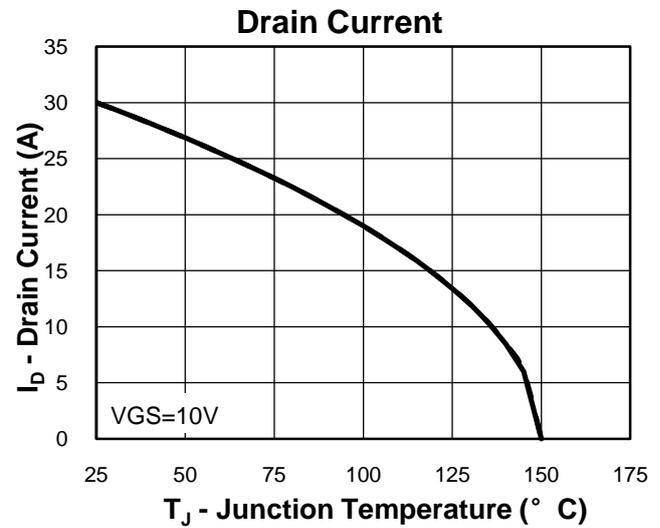
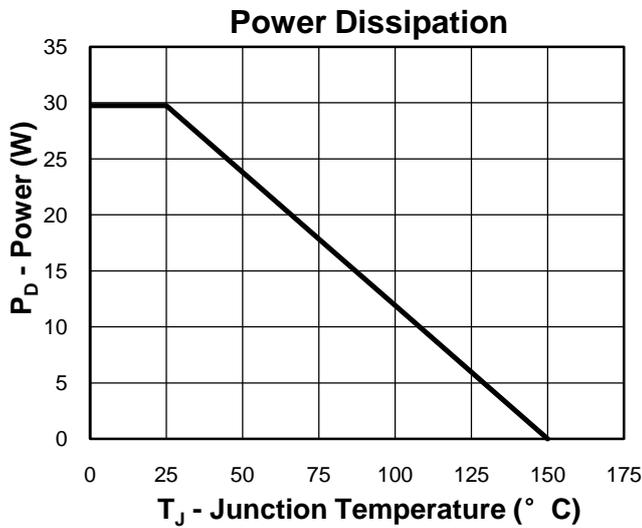


Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	4.5	°C/W
$R_{\theta JA}$ ^③	Thermal Resistance-Junction to Ambient	37	°C/W
Drain-Source Avalanche Ratings			
E_{AS} ^④	Avalanche Energy, Single Pulsed	30	mJ

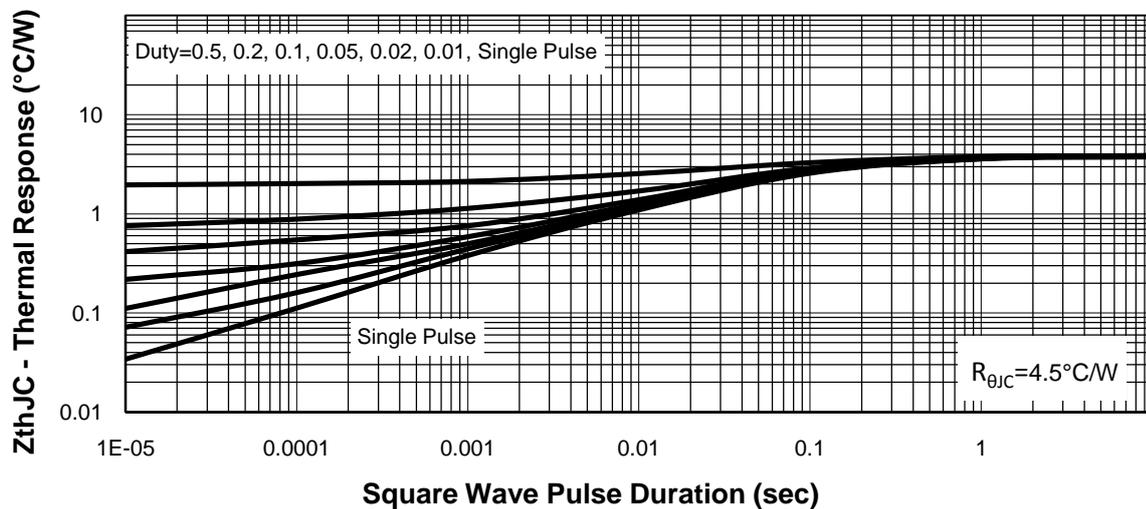
Electrical Characteristics ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V$			1	μA
		$T_J=125^\circ\text{C}$			30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.2	1.4	2.2	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
$R_{DS(ON)}$ ^⑤	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=20A$		7.5	9.0	m Ω
		$V_{GS}=4.5V, I_{DS}=15A$		9.3	12	m Ω
Diode Characteristics						
V_{SD} ^⑤	Diode Forward Voltage	$I_{SD}=20A, V_{GS}=0V$			1.2	V
t_{rr}	Reverse Recovery Time	$I_{SD}=20A, di_{SD}/dt=100A/\mu s$		13		ns
Q_{rr}	Reverse Recovery Charge			8		nC
Dynamic Characteristics ^⑥						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		1		Ω
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=15V,$ Frequency=1.0MHz		1007		pF
C_{oss}	Output Capacitance			128		
C_{riss}	Reverse Transfer Capacitance			117		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=15V, R_L=0.75\Omega,$ $I_{DS}=20A, V_{GEN}=10V,$ $R_G=3\Omega$		5.7		ns
t_r	Turn-on Rise Time			47		
$t_{d(OFF)}$	Turn-off Delay Time			31		
t_f	Turn-off Fall Time			23		
Gate Charge Characteristics ^⑥						
Q_g	Total Gate Charge	$V_{DS}=15V, V_{GS}=10V,$ $I_{DS}=20A$		23		nC
Q_{gs}	Gate-Source Charge			4.2		
Q_{gd}	Gate-Drain Charge			4.3		

Typical Characteristics

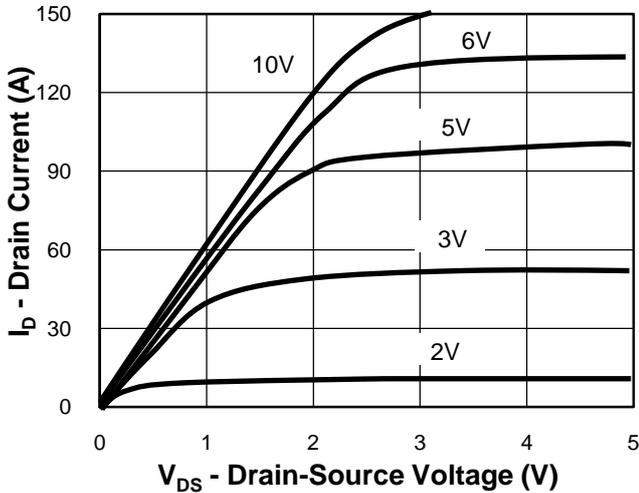


Thermal Transient Impedance

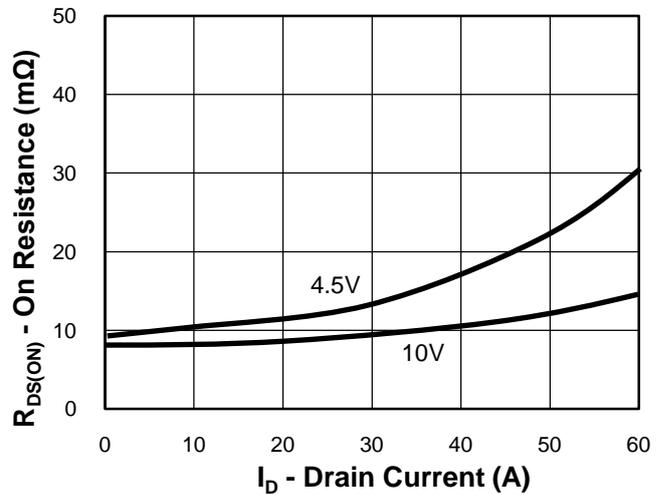


Typical Characteristics

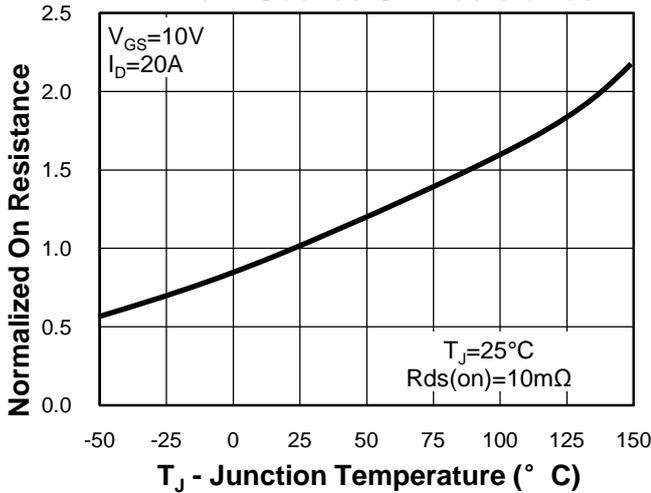
Output Characteristics



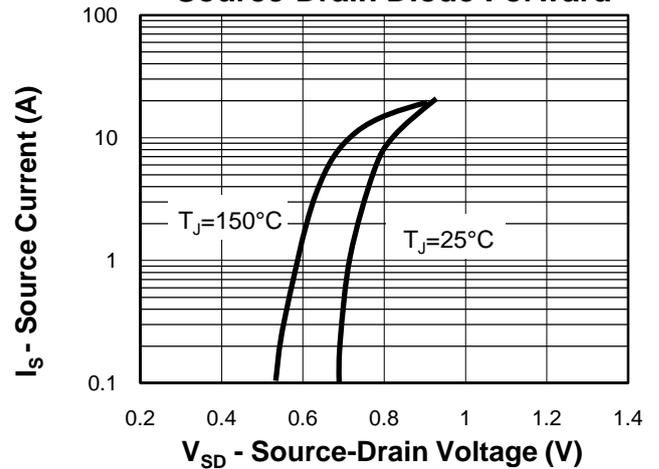
Drain-Source On Resistance



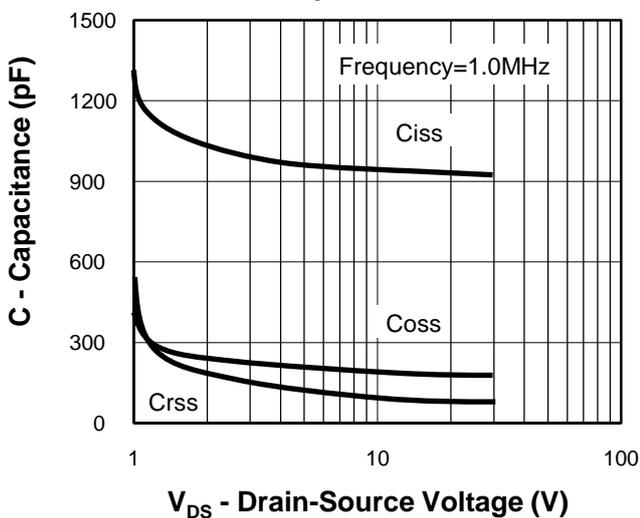
Drain-Source On Resistance



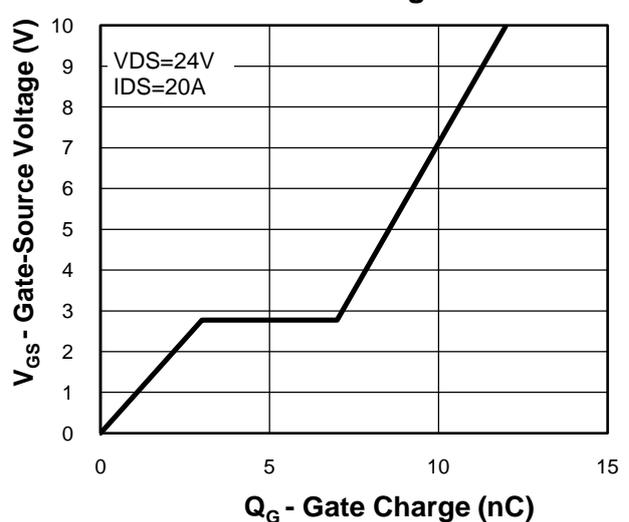
Source-Drain Diode Forward



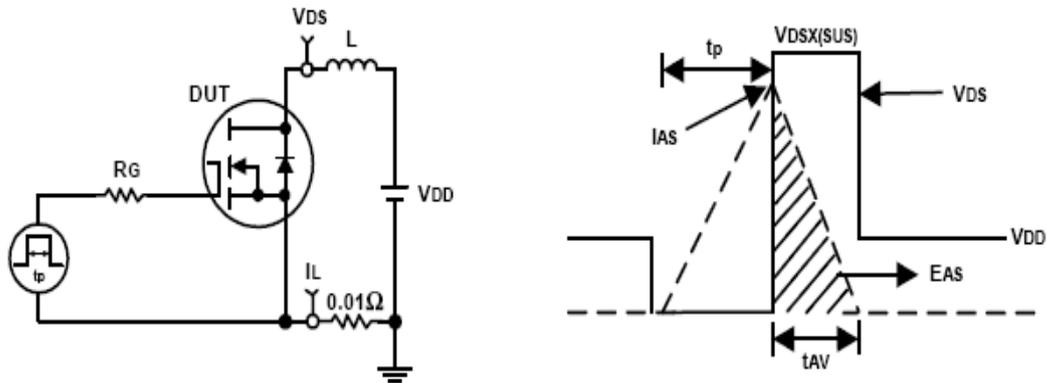
Capacitance



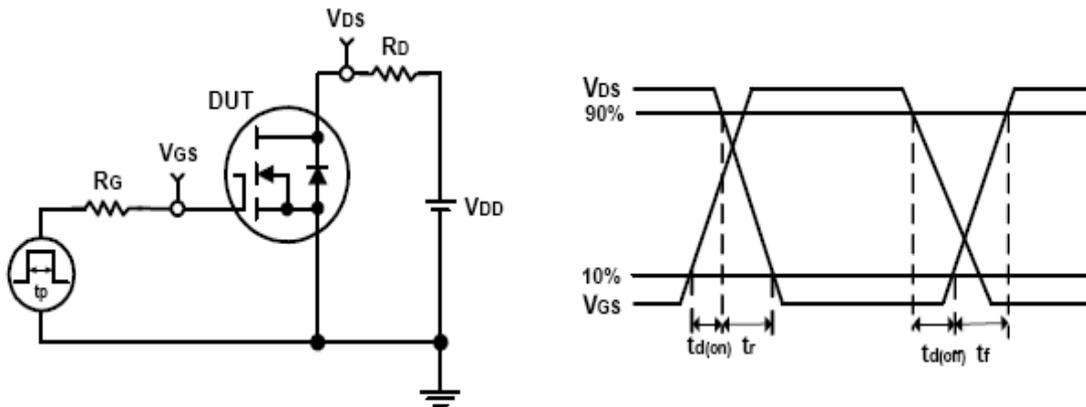
Gate Charge



Avalanche Test Circuit and Waveforms

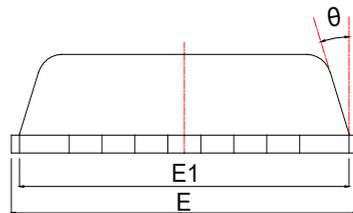
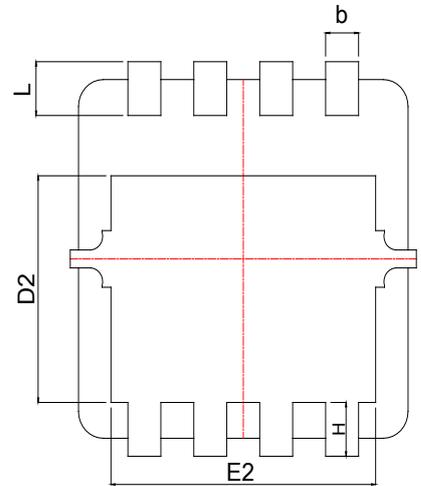
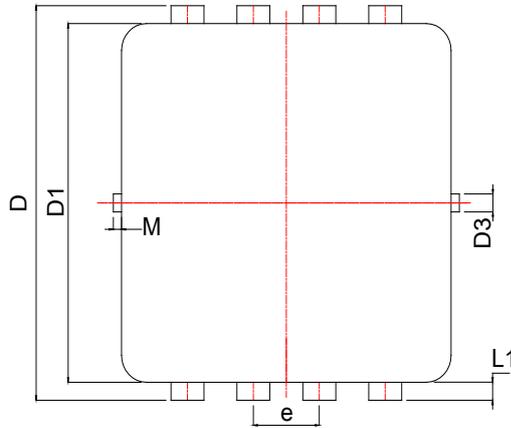
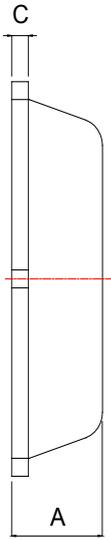


Switching Time Test Circuit and Waveforms

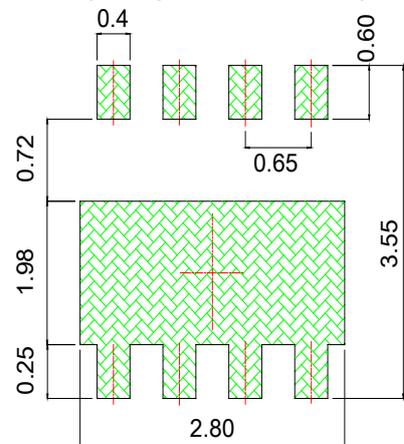


Package Information

PDFN3333



Land Pattern
(Only for Reference)



SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0.028	0.030	0.031	E1	3.00	3.15	3.20	0.118	0.122	0.126
b	0.25	0.30	0.35	0.010	0.012	0.014	E2	2.39	2.49	2.59	0.094	0.098	0.102
c	0.10	0.15	0.25	0.004	0.007	0.010	e	0.65BSC			0.026BSC		
D	3.25	3.35	3.45	0.128	0.132	0.136	H	0.30	0.40	0.50	0.012	0.016	0.020
D1	3.00	3.10	3.20	0.118	0.122	0.126	L	0.30	0.40	0.50	0.012	0.016	0.020
D2	1.78	1.88	1.98	0.070	0.074	0.078	L1	*	0.13	*	*	0.005	*
D3	*	0.13	*	*	0.005	*	θ	*	10°	12°	*	10°	12°
E	3.20	3.30	3.40	0.126	0.130	0.134	M	*	*	0.15	*	*	0.006

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[C3M0021120D](#) [DMN6022SSD-13](#)